



Sencio

Sencio BV, headquartered in Nijmegen, the Netherlands, is a highly qualified solutions and service provider for functional packaging in the semiconductor industry.

We develop and manufacture packages for semiconductor components and systems. State-of-the-art, TS16949 certified production and assembly lines in the Netherlands and the Philippines deliver everything from prototypes right up to volume runs of several million units per product.

Customized packages are delivered for a wide range of customers and applications, including but not limited to the automotive, industrial and medical markets. Their devices include sensors (optical, pressure, humidity, chemical, blood and ultrasonic), RF modules, opto-electronics/ photonics and MEMS. Calling on a range of technologies – from exposed die and QFN map moldings to our flagship nCapsulate – we can help you at any or all stages of package development for your device. Even when it comes to combining of electrical and mechanical components. Whether it is package development, prototyping or volume manufacture, or even taking care of your component supply management, we are here to support you from concept and throughout device lifetime.

Mission

Our mission is to be a world class competence center offering development and manufacturing of functional semiconductor assembly solutions. Collaborating with us will help you reduce the time between product conception and its introduction to the market place. By combining your expertise at system level with our creativity and know-how of packaging, we can make a winning team.

We delight in each new customer request, which offers us an opportunity to demonstrate our expertise in package technologies.



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Sencio 公司总部位于荷兰Nijmegen市，是半导体产业的功能封装服务和高端方案供应商。

我们为半导体元件和系统开发和生产封装产品。我们在荷兰及菲律宾有最新的经TS16949认证的生产和组装线，可以提供从原型开发到大批量生产的服务。

客户定制的封装产品多样，应用领域广泛，包括但不限于汽车、工业产品和医疗市场。客户的器件包括各种传感器（光学、压力、湿度、化学、血液和超声、RF模组、光电子和光子、MEMS等等。基于我们广泛的技术经验—从裸露芯片封装到QFN封装到我们的旗舰技术nCapsulate，我们可以给您的器件提供全阶段的封装开发服务，特别是机电结合元件。不管是封装开发、原型制造，还是批量生产，还是您器件的供应管理，我们都可以提供从概念到产品生命周期的服务支持。

我们的使命

我们的使命是成为具有世界水平和竞争力的功能半导体封装组装方案中心，提供开发和生产服务。与我们合作可以缩短您从产品概念到导入市场的时间。我们的创造性和封装技术诀窍与您的系统级经验相结合，可以使我们成为双赢团队。

客户新的要求会让我们非常愉悦，因为这是一个展示我们封装专业技术的机会。

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